

What is claimed is:

1. A method comprising:
 - a. generating a free radical; and
 - b. contacting a surface of a substrate having resin accretions thereon with the free radical to desmear the surface of the resin accretions and texture a resin.
2. The method of claim 1, wherein the free radical comprises a hydroxyl, halogen radical, or mixtures thereof.
3. The method of claim 1, wherein the free radical is generated electrolytically, chemically, by thermolysis, or by photolysis.
4. The method of claim 3, wherein the free radical is generated electrolytically at an electrical potential above an electrical potential for generating oxygen.
5. The method of claim 4, wherein the free radical is generated at a surface of an anode of an electrolytic cell.
6. The method of claim 2, wherein the hydroxyl radicals are generated from ozone or hydrogen peroxide or mixtures thereof.
7. The method of claim 3, wherein the free radical is generated chemically with a reagent comprising a ferrous salt and hydrogen peroxide.
8. A method of desmearing comprising:
 - a. generating a free radical;
 - b. contacting a surface of a substrate having resin accretions with the free radical to remove a portion of the resin accretions; and
 - c. contacting the surface of the substrate with a promoter to remove additional resin accretions from the surface of the substrate and texture a resin.
9. The method of claim 8, wherein the promoter comprises a permanganate etch solution.
10. The method of claim 8, wherein the substrate is a printed wiring board and the surface having the resin accretions is a through-hole wall.